SLOVENSKI STANDARD
SIST EN 61249-3-5:2001

01-marec-2001

Materials for printed boards and other interconnecting structures - Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Transfer adhesive films

Materials for printed boards and other interconnecting structures -- Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Transfer adhesive films

Materialien für Leiterplatten und andere Verbindungsstrukturen -- Teil 3-5: Rahmenspezifikation für unverstärkte, kaschierte und unkaschierte Basismaterialien (für flexible Leiterplatten) - Transfer-Kleberfilme für flexible Leiterplatten

Matériaux pour circuits imprimés et autres structures d'interconnexion -- Partie 3-5: Collection de spécifications intermédiaires pour les matériaux de base non renforcés, recouverts ou non (prévus pour les ciruits imprimés flexibles) - Films à transfert de colle

Ta slovenski standard je istoveten z: **EN 61249-3-5:1999**

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards

SIST EN 61249-3-5:2001 **en**

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 61249-3-5

April 1999

ICS 31.180

English version

Materials for printed boards and other interconnecting structures Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) Transfer adhesive films (IEC 61249-3-5:1999)

Matériaux pour circuits imprimés et autres structures d'interconnexion
Partie 3-5: Collection de spécifications intermédiaires pour les matériaux de base non renforcés, recouverts ou non (prévus pour les ciruits imprimés flexibles) - Films à transfert de colle
(CEI 61249-3-5:1999)

Materialien für Leiterplatten und andere Verbindungsstrukturen
Teil 3-5: Rahmenspezifikation für unverstärkte, kaschierte und unkaschierte Basismaterialien (für flexible Leiterplatten) Transfer-Kleberfilme für flexible Leiterplatten
(IEC 61249-3-5:1999)

This European Standard was approved by CENELEC on 1999-04-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC
European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 52/774/FDIS, future edition 1 of IEC 61249-3-5, prepared by IEC TC 52, Printed circuits, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61249-3-5 on 1999-04-01.

The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2000-01-01
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2002-01-01

Annexes designated "normative" are part of the body of the standard.
Annexes designated "informative" are given for information only.
In this standard, annex ZA is normative and annex A is informative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61249-3-5:1999 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60249-1	1982	Base materials for printed circuits Part 1: Test methods	EN 60249-1[1]	1993
IEC 60249-2-8	1987	Part 2: Specifications Specification No. 8: Flexible copper-clad polyester (PETP) film	EN 60249-2-8 + corr. March	1994 1994
IEC 60249-2-13	1987	Part 2: Specifications Specification No. 13: Flexible copper-clad laminated polyimide film, general purpose grade	EN 60249-2-13	1994
IEC 60249-2-15	1987	Part 2: Specifications Specification No. 15: Flexible copper-clad polyimid film, of defined flammability	EN 60249-2-15	1994
IEC 61189-2	1997	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 2: Test methods for materials for interconnection structures	EN 61189-2 + corr. August	1997 1997

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[1] EN 60249-1 includes A1:1984 + A2:1989 + A3:1991 to IEC 60249-1.

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Matériaux pour circuits imprimés et autres structures d'interconnexion –

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Commission Electrotechnique Internationale
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MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

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FOREWORD

1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.

2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.

3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical specifications, technical reports or guides and they are accepted by the National Committees in that sense.

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5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.

6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61249-3-5 has been prepared by IEC technical committee 52: Printed circuits.

The text of this standard is based on the following documents:

FDIS	Report on voting
52/774/FDIS	52/799/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This bilingual version (2001-05) replaces the English version.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

Annex A is for information only.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.